



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-31
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KKBR*UAU2AE5	A	Z6HA	2016-08-31
Amount	UoM	Unit type	ST ECOPACK Grade	
26.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x0.4	20	No lead	
Comment	Package: A0BR VFQFPN 20L 3X3 0,4 PTH; MDF valid for PM6697HTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KKBR*UAUZAES					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.696	mg	supplier	die	Silicon (Si)	7440-21-3		1.491	mg	879127	57346
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	2948	192
				supplier	metallization	Copper (Cu)	7440-50-8		0.123	mg	72524	4731
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	590	38
				supplier	metallization	Tungsten (W)	7440-33-7		0.007	mg	4127	269
				supplier	metallization	Nickel (Ni)	7440-02-0		0.015	mg	8844	577
				supplier	metallization	Platinum (Pt)	7440-06-4		0.009	mg	5307	346
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	2358	154
				supplier	Passivation	Silicon Oxide	7631-86-9		0.027	mg	15920	1038
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	590	38
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1769	115
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	5896	385
Leadframe	Copper & its alloys	8.701	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.395	mg	964832	322885
				supplier	alloy	Iron (Fe)	7439-89-6		0.196	mg	22526	7538
				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	230	77
				supplier	alloy	Zinc (Zn)	7440-66-6		0.011	mg	1264	423
				supplier	metallization	Nickel (Ni)	7440-02-0		0.087	mg	9999	3346
				supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	1034	346
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	115	38
Die attach	Other organic materials	0.252	mg	supplier	glue	Silver (Ag)	7440-22-4		0.172	mg	682540	6615
				supplier	glue	methylene diacrylate	42594-17-2		0.063	mg	250000	2423
				supplier	glue	Dicyclopentenylxyethyl methacrylate	68586-19-6		0.008	mg	31746	308
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.008	mg	31746	308
				supplier	glue	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.001	mg	3968	38
Bonding wires	Precious metals	0.126	mg	supplier	wire	Gold (Au)	7440-57-5		0.125	mg	992063	4808
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	7937	38
Encapsulation	Other organic materials	15.225	mg	supplier	wire	Silica, vitreous	60676-86-0		14.098	mg	925977	542231
				supplier	wire	epoxy resin	85954-11-6		0.609	mg	40000	23423
				supplier	wire	phenol resin	26834-02-6		0.457	mg	30016	17577
				supplier	tape	carbon black	1333-86-4		0.061	mg	4007	2346